

# SID

Factory: Rot am See

Article:

ML6

Provided:

Customer:

Date:

24.04.2026

**WÜRTH  
ELEKTRONIK**  
MORE THAN  
YOU EXPECT

Processtechnology: B: Pinlamination C: Pinlamination

Material Text	Mat. Nr.	µm		Stackup	Process overview
A-RS Kupferfolie-009my 330x490mm	50201012	9	VS	1	<div><div></div><div>A00B00C00</div></div>
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	62		2	
A-RS Kupferfolie-009my 330x490mm	50201012	35	L2	3	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	124		4	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		5	
C-RS-FR4-ML-0.356mm-035+035-TG150-HF-...	50203021	35	L3	6	
		356			
		35	L4		
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	124		7	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		8	
A-RS Kupferfolie-009my 330x490mm	50201012	35	L5	9	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	62		10	
A-RS Kupferfolie-009my 330x490mm	50201012	9	RS	11	

Thickness after Pressing

B00: 744 µm

Tol+: 75 µm

Tol-: 75 µm

Dmax: 819 µm

Dmin: 669 µm

C00: 890 µm

Tol+: 100 µm

Tol-: 100 µm

Dmax: 990 µm

Dmin: 790 µm

Thickness over all

0 µm

Tol+: 0 µm

Tol-: 0 µm

Dmax: 0 µm

Dmin: 0 µm

Demand for customer

Thickness (D): 1000 µm

Tol+: 100 µm

Tol-: 100 µm

Dmax: 1100 µm

Dmin: 900 µm

Measuring point: (05) over SM and galv. Cu; both sides

nominal: 886 µm

Version 1.2.20.35

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